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SDI Review Form 1.6

| Journal Name: | Journal of Engineering Research and Reports |
|---|---|
| Manuscript Number: | **Ms_JERR_46080** |
| Title of the Manuscript: | **Challenges and Resolution for Copper Wirebonding on Tapeless Leadframe Chip-On-Lead Technology** |
| Type of the Article | **Original Research Article** |

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This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound.
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**PART 1: Review Comments**

| | **Reviewer's comment** | **Author's comment** *(if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)* |
|---|---|---|
| **Compulsory** REVISION comments | **Compulsory revision is not required** | |
| **Minor** REVISION comments | Minor revision is not required | |
| **Optional/General** comments | The paper should be accepted | |

**PART 2:**

| | **Reviewer's comment** | **Author's comment** *(if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)* |
|---|---|---|
| **Are there ethical issues in this manuscript?** | *(If yes, Kindly please write down the ethical issues here in details)* | |

**Reviewer Details:**

| Name: | ***Snehadri B Ota*** |
|---|---|
| Department, University & Country | ***Institute of Physics, India*** |

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